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SPECIFICATION

PART NO. : LP6KL3-6K-1UTV892S09

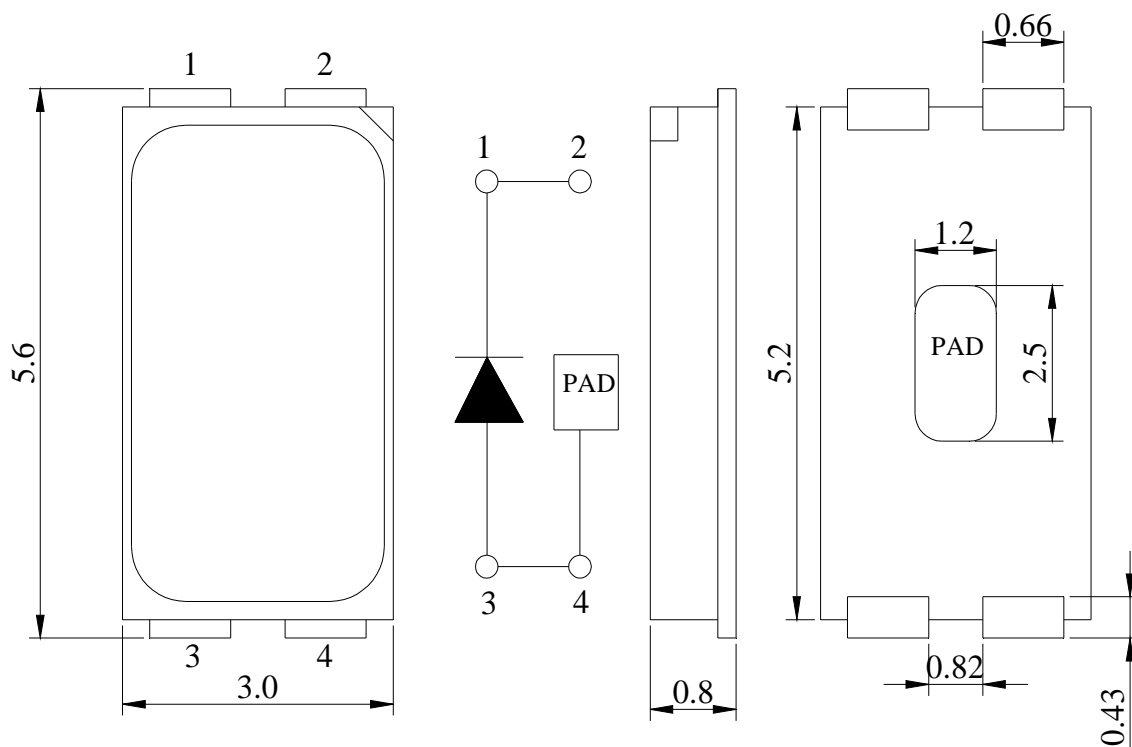
5.6 x 3.0mm SMD TYPE

CUSTOMER	LEDTECH
Confirmed by	Confirmed by
Date	Date



Approved by	Checked by	Prepared by
<i>Yue</i>	<i>Lian</i>	<i>Liang Dai</i>

Package Dimensions



Notes:

1. All dimensions are in mm.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without notice.
3. Tolerance is ± 0.25 mm unless otherwise noted.

Description

Part No.	LED Chip		Lens Color
	Material	Emitting Color	
LP6KL3-6K-1UTV892S09	InGaN	White	Yellow Diffused

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	P _d	594	mW
Reverse Voltage	V _r	5	V
D.C. Forward Current	I _f	180	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	I _f (Peak)	300	mA
Reverse Current	I _r	122	°C/W
ThermalResistance	R _{th J-S}	115	°C
Operating Temperature Range	Topr.	-40 to +100	°C
Storage Temperature Range	Tstg.	-40 to +100	°C
Soldering Temperature	Tsld.	Reflow Soldering: 260°C for 10 sec. Hand Soldering: 350°C for 3 sec.	
Electric Static Discharge Threshold (HBM)	ESD	2000	V

Electrical and Optical Characteristics:

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Flux	Φ _v	I _f =150mA	50		65	lm
Forward Voltage	V _f	I _f =150mA	3.1		3.3	V
Correlated Colour Temperature	CCT	I _f =150mA	7500		9000	K
Color Rendering Index(Ra)	CRI	I _f =150mA	70	-	-	Ra
Reverse Current	I _r	V _r =5V			10	μA
Viewing Angle	2θ 1/2	I _f =150mA		120		deg

Notes: 1.Tolerance of Luminous Intensity is ±15%

2.Tolerance of Forward Voltage is ±0.1V

3.Tolerance of Correlated Colour Temperature is ±10%

4.Tolerance of Color Rendering Index is ±2.

Bin range of Forward Voltage (IF=150mA)

Bin Code	Min.	Max.	Unit
b6	3.1	3.2	V
b7	3.2	3.3	

Bin range of Luminous Flux (IF=150mA)

Bin Code	Min.	Max.	Unit
F1	50	55	LM
F2	55	60	
F3	60	65	

Bin range of Correlated Colour Temperature (IF=150mA)

Bin Code	Min.	Max.	Unit
WK	7500	7750	K
WL	7750	8000	
WM	8000	8500	
WN	8500	9000	

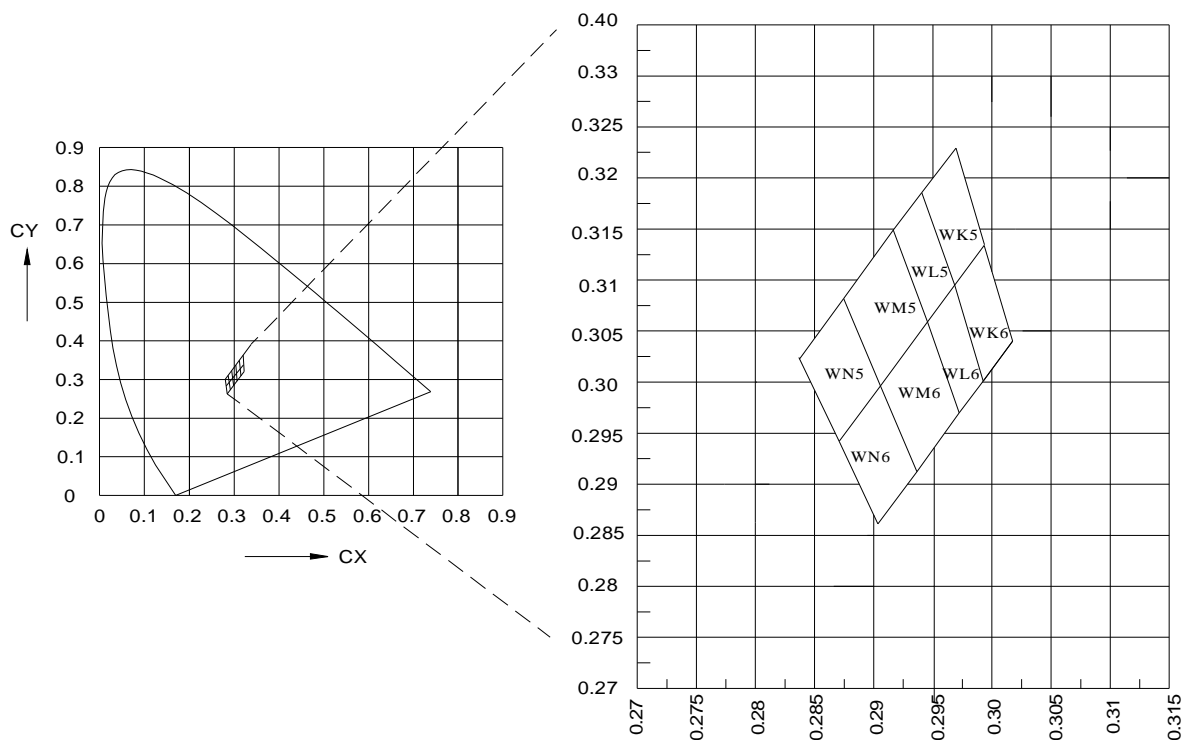
Chromaticity Coordinates Specifications for Bin Grading:

COLOR RANKS(IF=150mA.Ta=25°C)

BiN	RANK					BiN	RANK				
WK5	X	0.297	0.2995	0.2971	0.2946	WK6	X	0.297	0.2995	0.3019	0.2994
	Y	0.3093	0.3132	0.3226	0.3187		Y	0.3093	0.3132	0.3038	0.2999
WL5	X	0.2947	0.297	0.2946	0.292	WL6	X	0.2947	0.297	0.2994	0.2974
	Y	0.3057	0.3093	0.3187	0.3146		Y	0.3057	0.3093	0.2999	0.2968
WM5	X	0.2876	0.292	0.2947	0.2907	WM6	X	0.2907	0.2947	0.2974	0.2938
	Y	0.3078	0.3146	0.3057	0.2994		Y	0.2994	0.3057	0.2968	0.291
WN5	X	0.2838	0.2876	0.2907	0.2872	WN6	X	0.2872	0.2907	0.2938	0.2905
	Y	0.302	0.3078	0.2994	0.294		Y	0.294	0.2994	0.291	0.2859

Notes:X.Y Tolerance each Bin limit is±0.01.

Chromaticity Coordinates & Bin grading diagram:



Typical Electrical/Optical Characteristic Curves (25°C Ambient Temperature Unless Otherwise Noted)

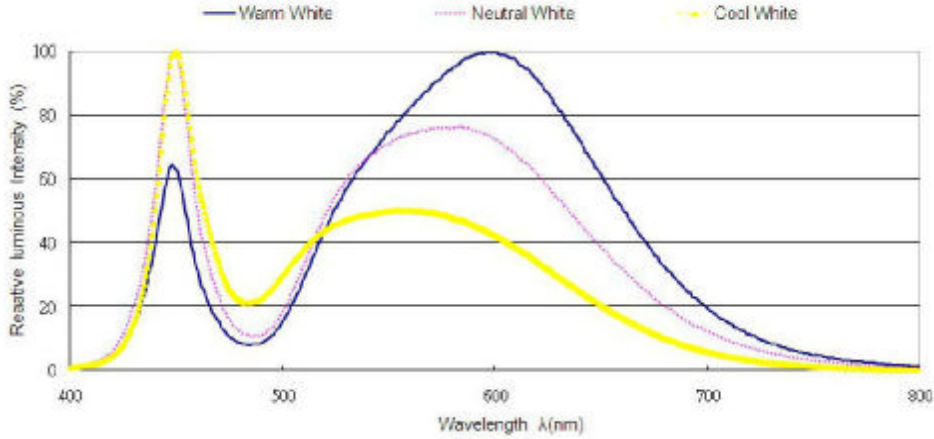
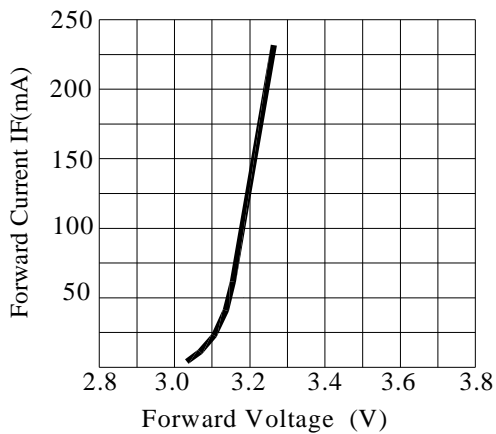
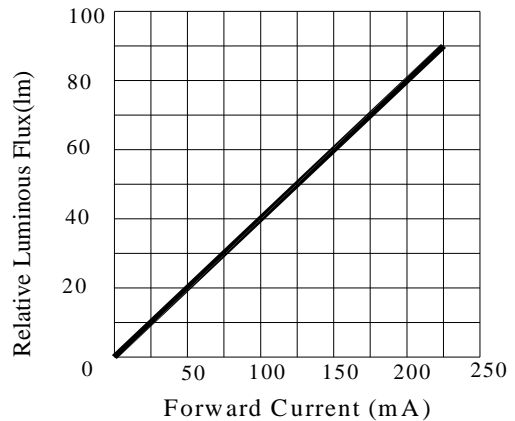


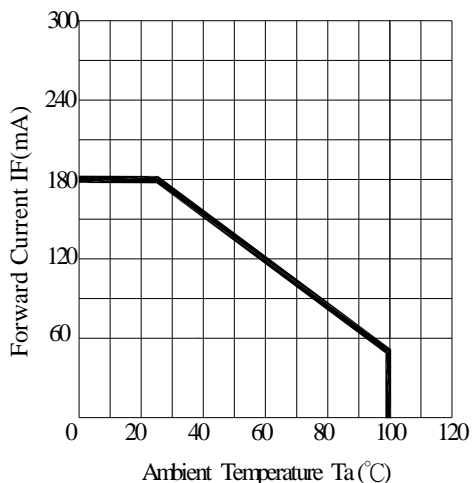
Fig.1 WHITE LED Spectrum VS. WAVELENGTH



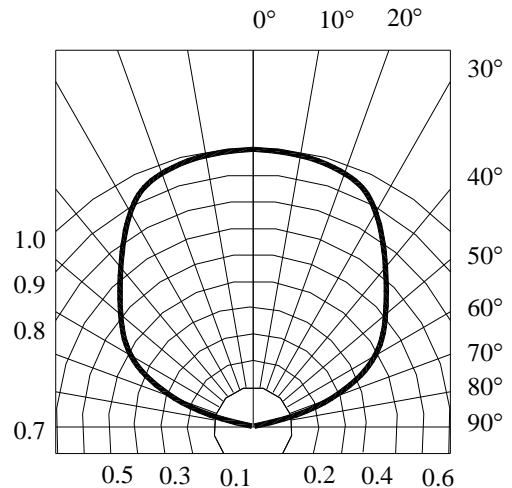
Forward Current VS. Applied Voltage



Forward Current VS. Luminous Flux



Ambient Temperature VS. Forward Current



Radiation Diagram

PRECAUTION IN USE

Storage

Recommended storage environment

Temperature: 5°C ~ 30°C (41°F ~ 86°F)

Humidity: 60% RH Max.

Moisture measures: Please refer to Moisture-sensitive label on reels package bags.

If unused LEDs remain, they should be stored in moisture proof packages, such as sealed container with packages of moisture absorbent material (silica gel). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again.

Fold the opened bag firmly and keep in dry environment.

Soldering

	Reflow Soldering		Hand Soldering	
	Lead Solder	Lead – free Solder		
Pre-heat	120~150°C	180~200°C	Temperature	350°C Max.
Pre-heat time	120sec. Max.	120sec. Max.	Soldering time	3sec. Max.
Peak temperature	240°C Max.	260°C Max.		(one time only)
Soldering time	10sec. Max.	10sec. Max.		
Condition	refer to Temperature-profile 1	refer to Temperature-profile 2		

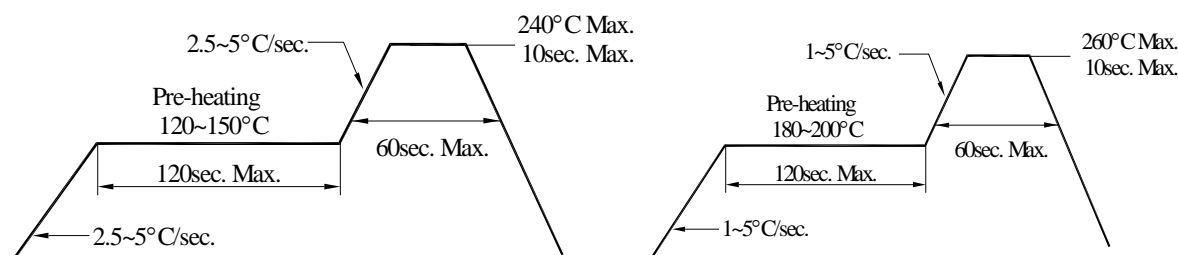
*After reflow soldering rapid cooling should be avoided.

[Temperature-profile (Surface of circuit board)]

Use the conditions shown to the under figure.

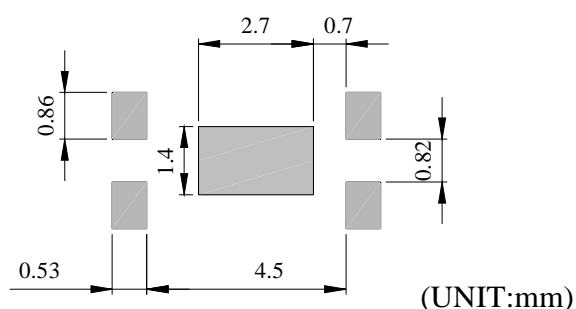
< 1 : Lead Solder >

< 2 : Lead-free Solder >



[Recommended soldering pad design]

Use the following conditions shown in the figure.



Sulfur-sensitive

- **There is silver-plated metal part on the inner/outer side of the outer package. If exposed to the condition with corrosive gas, the silver plating surface may go bad, which will affect soldering strength and optical properties. Therefore, after opening it must be kept in a sealed container, etc.**
- **Materials contain sulfur component (gasket, adhesive, etc.) may have bad effects on the surface of the coating, so please do not use such materials in the product.**
- **In cardboard boxes and rubber, even in the atmosphere may contain minute amount of corrosive gases; In addition, the resin material may also contain halogen which has a bad effect on the surface of the coating.**
- **Even if the soldering installation and product assembly finished, by the effect of corrosive gas generated by relative materials of LED and external injected, the coating surface may go bad, so it is necessary to design the product taking into account the above factors.**
- **If requires, it is best to use a silicone washer, but be aware that low molecular silicone may cause the product poor contact.**
- **Keep the product in location where has less temperature change, because moisture condensation would be generated under a condition of strong temperature change.**

DISCLAIMER

- 1. Our department reserves the right(s) on the adjustment of product material mix for the specification.**
- 2. The product meets our department published specification for a period of twelve (12) months from date of shipment.**
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.**
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Our department assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.**
- 5. These specification sheets include materials protected under copyright of our department. Reproduction in any form is prohibited without obtaining our department's prior consent.**
- 6. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized our department sales agent for special application request.**

Handling of Silicone Resin LEDs

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound

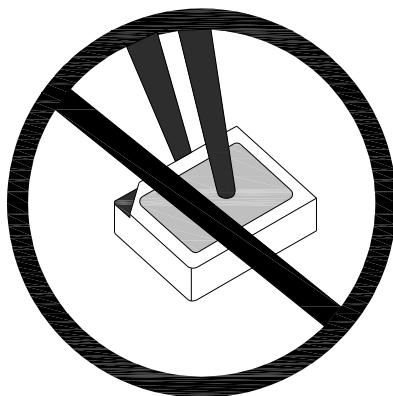


Figure 1

In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

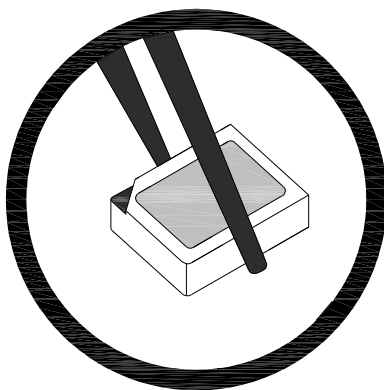
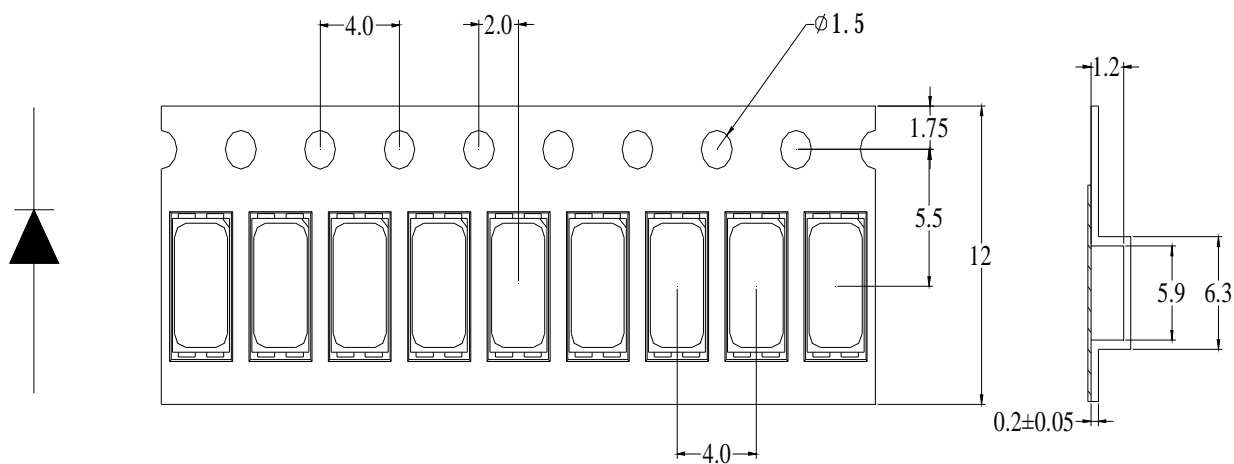


Figure 2

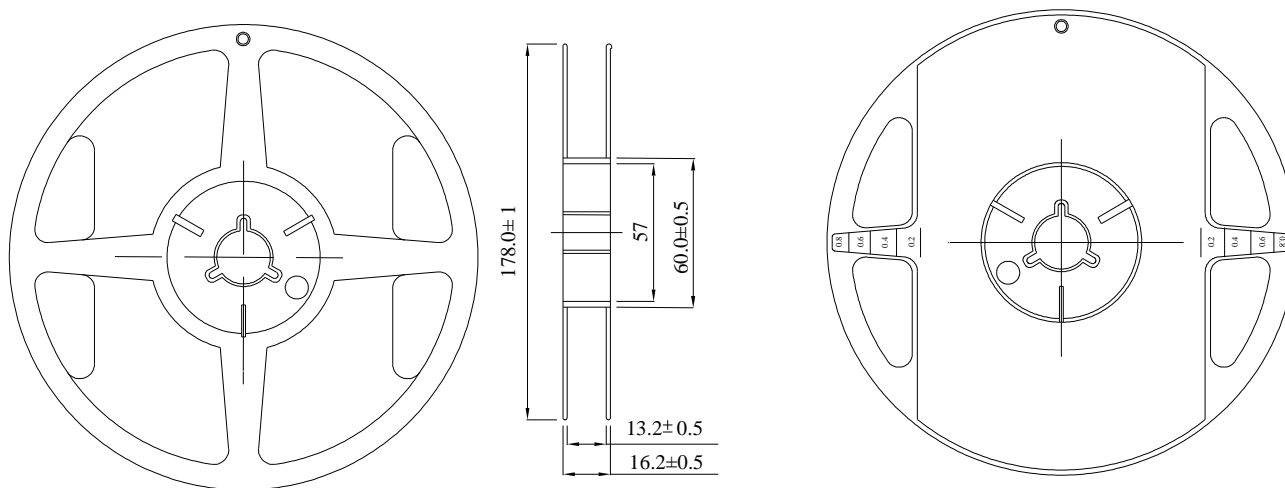
When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented.

This is assured by choosing a pick and place nozzle which is larger than the LED's reflector area.

Dimensions for Tape (mm)



Dimensions for Reel



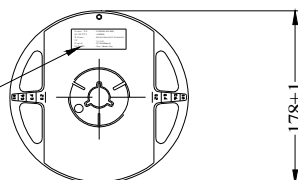
Notes:

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Packing

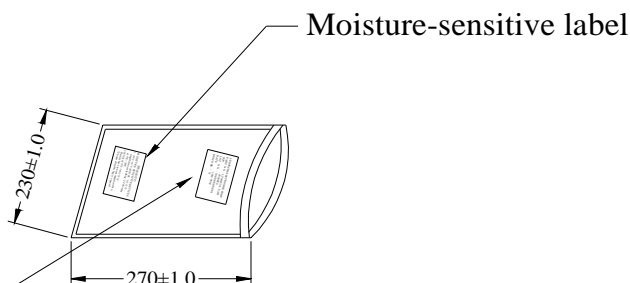
REEL
QUANTITY: 3,000 PCS

LEDTECH ELECTRONICS CORP.
PART NO :LTXXXX-XX
Q'TY : PCS
LOT NO :XXXXXXXXXX
DATE :
BIN CODE:



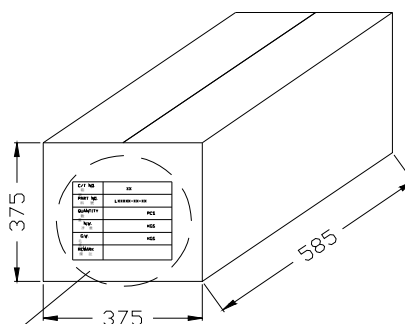
BAG
QUANTITY: 3,000 PCS

LEDTECH ELECTRONICS CORP.
PART NO :LTXXXX-XX
Q'TY : PCS
LOT NO :XXXXXXXXXX
DATE :
BIN CODE:



OUTER CARTON:
QUANTITY: 56 BAGS
TOTAL: 168,000PCS

C/T NO. 箱 號	XX
PART NO. 料 號	XXXXXXXXXXXXXXXX
QUANTITY 數 量	PCS
N.W. 淨 重	KGS
G.W. 毛 重	KGS
REMARK 備 註	



Notes:

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COMPONENT MATERIALS AND CONSTRUCTION:

NO.	ITEM	MATERIAL	廠商
1	BONDING WIRE	GOLD 1.25mil /Au > 99.99%	賀利氏
2	LED CHIP	InGaN	乾照
3	ADHESIVE	EPOXY	嵩越
4	LENS	Silicon	康美特
5	PACKEGE	PA9T-TA112	博羅
6	METALS	C194(銀包銅)	博羅

